


CT 00-020
PATENT**Drawings**

New FIG. 3 is presented herein.

Clean Version of Amended Portion of Specification

Please insert the following amended paragraph, for the paragraph beginning on page 13, line 15, through page 14, line 6 of the originally presented specification.



Referring additionally to FIG. 9, it can be seen that mounting pads 43 are formed with a surface area that is larger than the lower adjoining surface area of the associated via 32. As an example, if via 32 is formed with a rectangular cross-sectional area having a maximum side dimension of approximately 125 μ m, the surface area of mounting pad 43 may be generally rectangular with a length to width ratio of about 2:1. Solder (e.g., solder paste, etc.) is prepositioned on mounting pad 43, by solder printing or the like, to achieve a desired amount. The structure is then heated in a well known fashion to melt or reflow the solder paste or solder positioned on mounting pad 43. The prepositioned solder wicks-up the outside of via 32 to form a fillet 45, as illustrated in FIG. 8. The amount of prepositioned solder is selected so that the final standoff height h_s is preferably in a range of from 75 μ m to 125 μ m. This range allows the solder associated with the module to be printed at the same time as solder for other board elements or modules and the entire substrate 40 can be printed in one step.